

CLAIMS

1. A protective tape applying and separating method for applying protective tape to a surface of a semiconductor
5 wafer with a pattern formed thereon, and separating the protective tape from the surface of the semiconductor wafer, said protective tape applying and separating method being characterized by comprising:
 - an applying step for applying a plurality of protective
10 tapes in plies to the surface of said semiconductor wafer such that a protective tape with weak adhesion lies on top; and
 - a separating step for applying a separator tape over said protective tapes applied in plies, and separating the
15 protective tapes in plies one by one, the upper one first, from the surface of said semiconductor wafer by means of the separator tape.
2. A protective tape applying and separating method as
20 defined in claim 1, characterized in that said protective tapes applied to the surface of the semiconductor wafer comprise a plurality of protective tapes bonded together in plies as a unit beforehand.
- 25 3. A protective tape applying and separating method as

defined in claim 2, characterized in that said protective tapes are in sheet form, said protective tapes being first applied to the semiconductor wafer, and thereafter cut approximately to the shape of the semiconductor wafer.

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4. A protective tape applying and separating method as defined in claim 2, characterized in that said protective tapes are cut approximately to the shape of the semiconductor wafer beforehand.

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5. A protective tape applying and separating method as defined in claim 1, characterized in that said protective tapes in plies are a plurality of protective tapes applied individually and repeatedly.

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6. A protective tape applying and separating method as defined in claim 5, characterized in that said protective tapes are in sheet form, said protective tapes being first applied to the semiconductor wafer, and thereafter cut approximately to the shape of the semiconductor wafer.

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7. A protective tape applying and separating method as defined in claim 5, characterized in that said protective tapes are cut approximately to the shape of the semiconductor wafer beforehand.

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8. A protective tape applying and separating method as defined in claim 1, characterized in that said protective tapes in plies have adhesive-contacting surfaces given
5 release treatment.

9. A protective tape applying and separating method as defined in claim 8, characterized in that said protective tapes are in sheet form, said protective tapes being first
10 applied to the semiconductor wafer, and thereafter cut approximately to the shape of the semiconductor wafer.

10. A protective tape applying and separating method as defined in claim 8, characterized in that said protective
15 tapes are cut approximately to the shape of the semiconductor wafer beforehand.

11. A protective tape applying and separating method for applying protective tape to a surface of a semiconductor
20 wafer with a pattern formed thereon, and separating the protective tape from the surface of the semiconductor wafer, said protective tape applying and separating method being characterized by comprising:

an applying step for applying a plurality of protective
25 tapes of the same type with adhesive-contacting surfaces

given release treatment, in plies to the surface of said semiconductor wafer; and

a separating step for applying a separator tape over said protective tapes applied in plies, and separating the protective tapes in plies one by one, the upper one first, from the surface of said semiconductor wafer by means of the separator tape.

12. A protective tape applying and separating method as defined in claim 11, characterized in that said protective tapes applied to the surface of the semiconductor wafer comprise a plurality of protective tapes bonded together in plies as a unit beforehand.

13. A protective tape applying and separating method as defined in claim 12, characterized in that said protective tapes are in sheet form, said protective tapes being first applied to the semiconductor wafer, and thereafter cut approximately to the shape of the semiconductor wafer.

14. A protective tape applying and separating method as defined in claim 12, characterized in that said protective tapes are cut approximately to the shape of the semiconductor wafer beforehand.

15. A protective tape applying and separating method as defined in claim 11, characterized in that said protective tapes in plies are a plurality of protective tapes applied individually and repeatedly.

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16. A protective tape applying and separating method as defined in claim 15, characterized in that said protective tapes are in sheet form, said protective tapes being first applied to the semiconductor wafer, and thereafter cut
10 approximately to the shape of the semiconductor wafer.

17. A protective tape applying and separating method as defined in claim 15, characterized in that said protective tapes are cut approximately to the shape of the semiconductor wafer beforehand.
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